Preferred Device

SWITCHMODETM **Power Rectifier**

D²PAK Surface Mount Power Package

The D²PAK Power Rectifier employs the Schottky Barrier principle with a platinum barrier metal. These state-of-the-art devices have the following features:

- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL94, VO at 1/8"
- Short Heat Sink Tab Manufactured Not Sheared!
- Similar in Size to the Industry Standard TO-220 Package

Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL94, VO
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 units per plastic tube
- Available in 24 mm Tape and Reel, 800 units per 13" reel by adding a "T4" suffix to the part number
- Marking: B2545
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)

Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS (Per Leg)

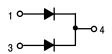
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	45	V
Average Rectified Forward Current (Rated V _R , T _C = 130°C) Total Device	I _{F(AV)}	15 30	Α
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 130^{\circ}C$)	I _{FRM}	30	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	А
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I _{RRM}	1.0	Α
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature	T _J	-65 to +150	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

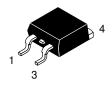


ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 30 AMPERES **45 VOLTS**





D²PAK **CASE 418B** STYLE 3

MARKING DIAGRAM



B2545 = Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB2545CT	D ² PAK	50/Rail
MBRB2545CTT4	D ² PAK	800/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value

1

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction to Case — Junction to Ambient (Note 1.)	$R_{ hetaJC} \ R_{ hetaJA}$	1.5 50	°C/W

ELECTRICAL CHARACTERISTICS (Per Leg)

Maximum Instantaneous Forward Voltage (Note 2.)	VF	0.73	Volts
$(i_F = 30 \text{ Amps}, T_J = 125^{\circ}\text{C})$		0.82	
$(i_F = 30 \text{ Amps}, T_J = 25^{\circ}\text{C})$			
Maximum Instantaneous Reverse Current (Note 2.)	i _R	40	mA
(Rated dc Voltage, T _J = 125°C)		0.2	
(Rated dc Voltage, $T_{i,l} = 25^{\circ}C$)			

- 1. When mounted using minimum recommended pad size on FR-4 board.
- 2. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

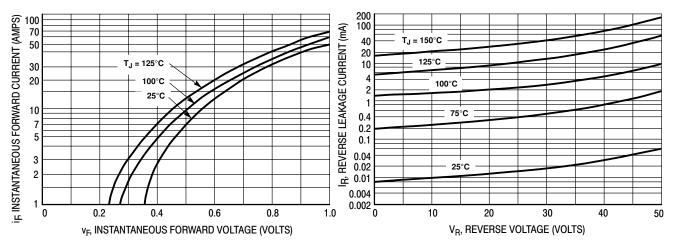


Figure 1. Typical Forward Voltage, Per Leg

Figure 2. Typical Reverse Current, Per Leg

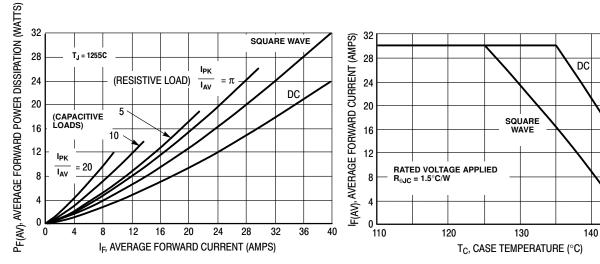


Figure 3. Typical Forward Power Dissipation

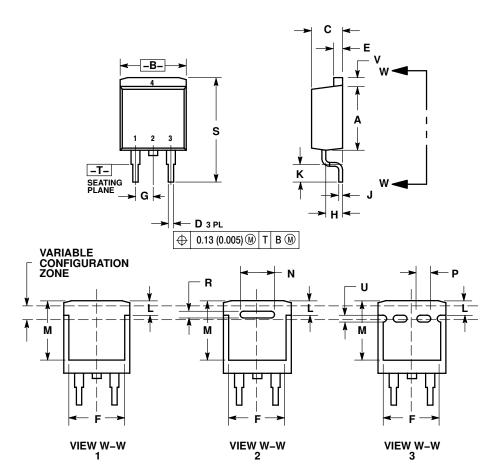
Figure 4. Current Derating, Case

150

PACKAGE DIMENSIONS

D²PAK

CASE 418B-04 **ISSUE H**

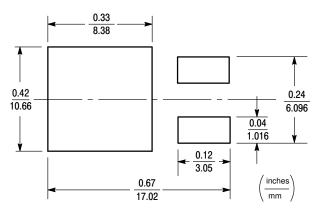


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
Р	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40

- STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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